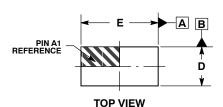
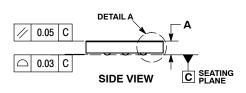


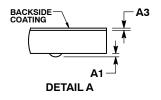


WLCSP6 0.86x1.70x0.265 CASE 567UK **ISSUE A**

DATE 22 MAY 2017







NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF CONTACT BALLS. COPLANARITY APPLIES TO SPHERICAL CROWNS
- OF CONTACT BALLS.
 DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.24	0.265	0.29	
A1	0.04 REF			
АЗ	0.025 REF			
b	0.12	0.17	0.22	
D	0.81	0.86	0.91	
Е	1.65	1.70	1.75	
е	0.40 BSC			

GENERIC MARKING DIAGRAM*



= Assembly Location

= Wafer Lot

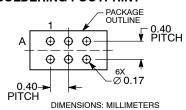
Υ = Year

W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

е \oplus Ф \oplus 6x ∅ b 0.05 CAB 0.03 С **BOTTOM VIEW**

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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